

## APPENDIX

## SPECIFICATION PARAGRAPH(S) SHOWING AMENDED WORDING:

None.

## CLAIMS AMENDED SHOWING AMENDMENTS THERETO:

16. (Amended) A solderable flexible adhesive interposer comprising:  
at least one layer of flexible dielectric adhesive having a modulus of elasticity less than about 35,000 kg/cm<sup>2</sup> (about 500,000 psi),  
a plurality of conductive vias through said layer of flexible dielectric adhesive, said plurality of conductive vias being of a flexible electrically conductive adhesive having a modulus of elasticity less than about 35,000 kg/cm<sup>2</sup> (about 500,000 psi) and being in a pattern adapted for connection to contacts of [one of an electronic device and a substrate,] an electronic device or a substrate, and  
a solderable electrically conductive metal formed on at least one exposed surface of said conductive vias and in electrical contact therewith,  
wherein at least one end of the plurality of conductive vias includes contacts adapted to be soldered to [one of an electronic device and a substrate] an electronic device or a substrate.
23. (Amended) A solderable flexible adhesive interposer comprising:  
a plurality of layers of flexible dielectric adhesive having a modulus of elasticity less than about 35,000 kg/cm<sup>2</sup> (about 500,000 psi);  
a plurality of conductive vias through each of said layers of flexible dielectric adhesive, said plurality of conductive vias being of a flexible electrically conductive adhesive having a modulus of elasticity less than about 35,000 kg/cm<sup>2</sup> (about 500,000 psi), said conductive vias in an exposed one of said plurality of flexible dielectric adhesive layers being in a pattern adapted for connection to contacts of [one of an electronic device and a substrate;] an electronic device or a substrate;  
a solderable electrically conductive metal formed on an exposed surface of said conductive vias of the exposed one of said flexible dielectric adhesive layers and in electrical contact therewith, wherein at least one end of the plurality of conductive vias includes contacts adapted to be soldered to [one of an electronic device and a substrate;] an electronic device or a substrate;  
said plurality of conductive vias in each said layer of flexible dielectric adhesive being in a pattern corresponding at least in part to a pattern of said plurality of conductive vias of the adjacent layers of said flexible dielectric adhesive; and  
a conductor residing between at least two of said adjacent layers of flexible dielectric adhesive, wherein said conductor is patterned and is in electrical contact with ones of said conductive vias of each of the at least two of said layers of flexible

dielectric adhesive.

31. (Amended) [The panel of a plurality of electronic devices of claim 30] A panel of a plurality of electronic devices having a pattern of contacts thereon and solderable flexible adhesive connections formed on the contacts comprising:  
    a layer of an oxidation-resistant metal on the contacts of the electronic devices of said panel;  
    a plurality of electrically conductive bumps formed of a flexible electrically conductive adhesive having a modulus of elasticity less than about 35,000 kg/cm<sup>2</sup> (about 500,000 psi), wherein said plurality of bumps is deposited on the oxidation resistant layer in the pattern of contacts of the electronic device; and  
    a solderable electrically conductive metal layer formed on an exposed surface of said electrically conductive bumps distal the contacts of the electronic devices and in electrical contact therewith,  
    wherein said panel includes one of a semiconductor wafer having a plurality of semiconductor devices formed therein and a panel of electrical substrates having a plurality of electrical substrates formed therein.